

300mm Semi-Automatic BG Tape Laminator

# RAD-3500m/12



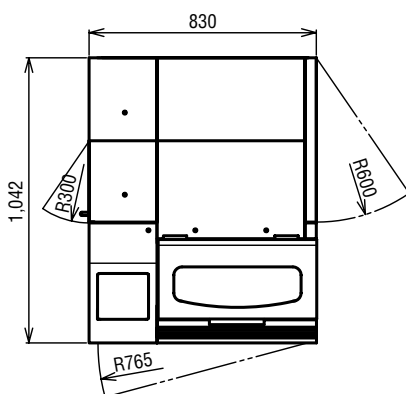
## Outline

- Semi-automatic BG Tape laminator.
- Once the operator supplies the wafer, back grinding tape lamination and tape cutting around the wafer periphery are performed.
- As an option, a heater function maybe added to tables and press rollers.

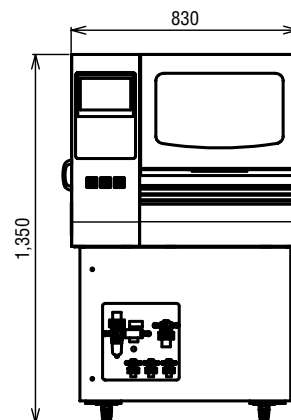
Suitable Tapes · BG Tape : Adwill E series, P series

## External View

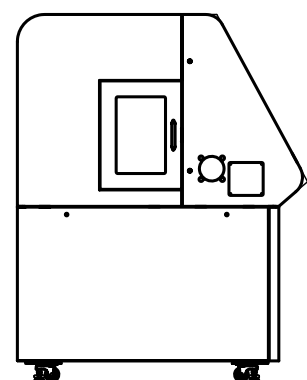
Unit:mm



Top View



Front View



Left Side View

## Facility

<b>Power Supply</b>	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
<b>Air Supply</b>	Capacity	: 0.7kW
	Air pressure	: 0.5-0.8MPa
	Air consumption	: >130L/min (ANR)

**Applicable Wafer Size** 150mm, 200mm, 300mm

**Size**  
Width : 830mm  
Depth : 1,042mm  
Height : 1,350mm

**Weight** 250kg

**Processing Capacity** 40sec/wafer (excludes setting time)



**LINTEC Corporation** *Linking your dreams*

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